

SOLDER, MICROELECTROMECHANICAL COMPONENT AND DEVICE, AND A  
PROCESS FOR PRODUCING A COMPONENT OR DEVICE

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ABSTRACT

A solder, in particular a thin-film solder, for joining microelectromechanical components, wherein the solder is a eutectic mixture of gold and bismuth. Components and devices joined by a solder of this type are also disclosed, in addition to processes for producing such components or devices.